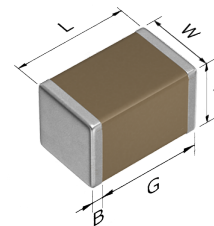


# 积层贴片陶瓷片式电容器

C2012X6S1H225K125AB

RoHS Reach Halogen Free Pb Free

交货型号	C2012X6S1H225KT****
用途	一般等级
特点	<b>General</b> 一般 (~75V)
系列	C2012 [EIA 0805]
状态	量产体制(新设计非推荐) 推荐代替型号 : <a href="#">C2012X7R1H225K125AC</a> (不保证其兼容性。)



## 尺寸

长度(L)	2.00mm ±0.20mm
宽度(W)	1.25mm ±0.20mm
厚度(T)	1.25mm ±0.20mm
端子宽度(B)	0.20mm Min.
端子间隔(G)	0.50mm Min.
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

## 电气特性

电容	2.2 μF ±10%
额定电压	50VDC
温度特性	X6S (±22%)
耗散因数 (Max.)	5%
绝缘电阻 (Min.)	227MΩ

## 其他

焊接方法	流体 回流
AEC-Q200	NO
包装形式	塑封编带 (180mm卷筒)
包装个数	2000pcs

! Images are for reference only and show exemplary products.

! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

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特性图表 (这是参考数据，并不保证产品的特性。)

## Associated Images

